

# 100 $\mu$ PET test-chip

## Description




Test-chip for the 100 $\mu$ PET project.

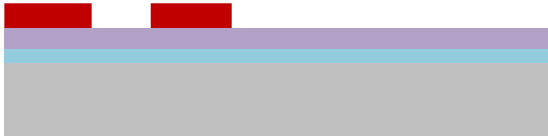


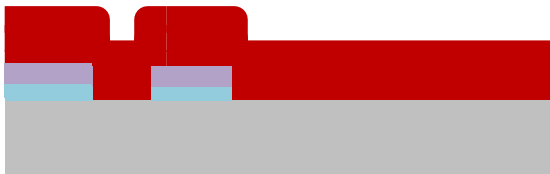
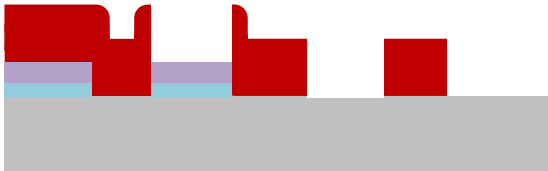
Neural Microsystems Platform's machine needed
Plasma etcher (PINK), Sputter (AC 450), Semi-Automatic Coater, Mask exposure (MLA), developer, Dry etcher (Corial)
Substrate Type
4-inch Si wafer

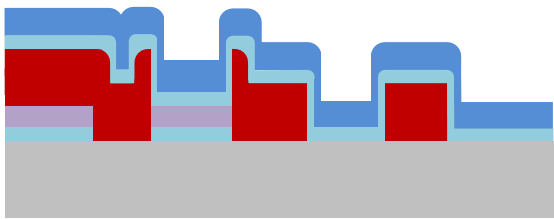
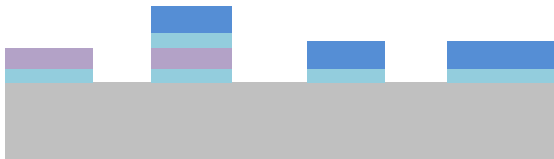
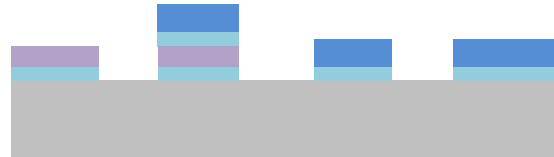
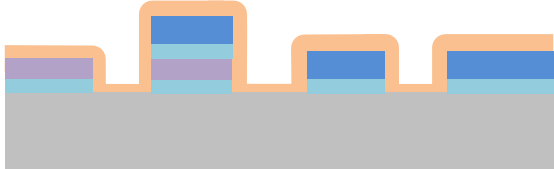
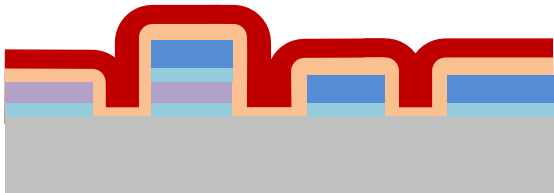
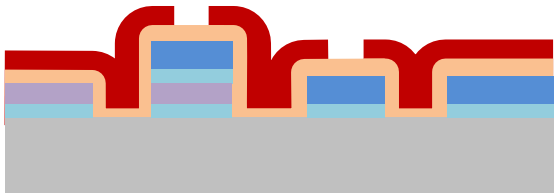
## Process Outline

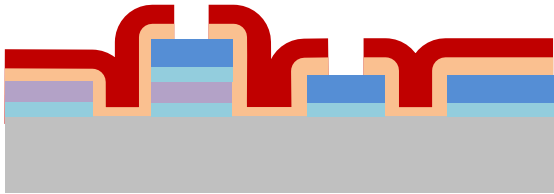
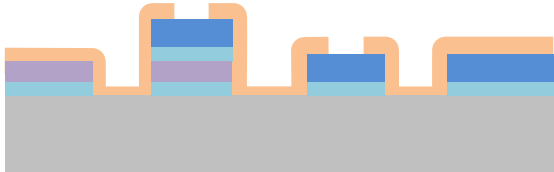
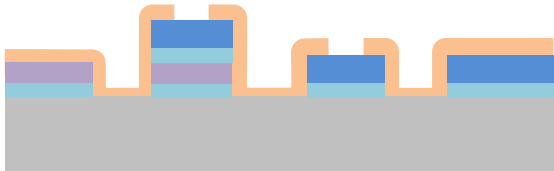
### Color chart

Si	Ti	Pt	PR	Al	SiO <sub>2</sub>
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01	<b>Surface Preparation</b> <u>Machine</u> : Plasma etcher (PINK) <u>Recipe</u> : 2min_High	
02	<b>Metal deposition</b> 10 nm Ti + 100 nm Pt <u>Machine</u> : Sputter (AC 450) <u>Recipe</u> :	
03	<b>Dehydration &amp; PR Coating</b> Hot plate: 1min @ 110°C <u>Machine</u> : Semi_auto_coater <u>Recipe</u> : <u>Baking</u> :	

04	<p>Mask Exposure + Develop</p> <p>Machine: MLA + developer</p> <p>Layer to expose:</p> <ul style="list-style-type: none"><li>Layer #3</li></ul> <p>Invert Mask polarity:</p> <p>Exposure window:</p> <p>40</p> <p>-40            40</p> <p>-40</p> <p>Dose:</p> <p>Development:</p>															
05	<p>Dry Etching</p> <p>Machine: Corial</p> <p>Recipe:</p> <p>Time:</p>															
06	<p>PR Stripping</p> <p>Ultrasonic bath &amp; Acetone</p>															
07	<p>Dehydration &amp; PR Coating</p> <p>Hot plate: 1min @ 110°C</p> <p>Machine: Semi_auto_coater</p> <p>Recipe:</p> <p>Baking:</p>															
08	<p>Mask Exposure + Develop</p> <p>Machine: MLA + developer</p> <p>Layer to expose:</p> <ul style="list-style-type: none"><li>Layer #134</li></ul> <p>Invert Mask polarity:</p> <p>Exposure window: See #04</p> <p>Alignment Cross:</p> <table><tr><td>X</td><td>Y</td></tr><tr><td>24000</td><td>36000</td></tr><tr><td>33000</td><td>18000</td></tr><tr><td>33000</td><td>-18000</td></tr><tr><td>-24000</td><td>-36000</td></tr><tr><td>-33000</td><td>-18000</td></tr><tr><td>-33000</td><td>18000</td></tr></table> <p>Dose:</p> <p>Development:</p>	X	Y	24000	36000	33000	18000	33000	-18000	-24000	-36000	-33000	-18000	-33000	18000	
X	Y															
24000	36000															
33000	18000															
33000	-18000															
-24000	-36000															
-33000	-18000															
-33000	18000															

09	<p><b>Metal deposition</b>          10 nm Ti + 300 nm Al  <u>Machine:</u> Sputter (AC 450)  <u>Recipe:</u></p>	
10	<p><b>Lift off</b>  <u>Ultrasonic bath &amp; Acetone</u></p>	
11	<p><b>Dehydration</b>  <u>Machine:</u> Hot plate  <u>Recipe:</u> 110°C – 1 min</p>	
12	<p><b>Passivation coating</b>          300 nm SiO<sub>2</sub>  <u>Machine:</u> Sputter (AC 450)  <u>Recipe:</u>  <u>Baking:</u></p>	
13	<p><b>Dehydration &amp; PR Coating</b>          Hot plate: 1min @ 110°C  <u>Machine:</u> Semi_auto_coater  <u>Recipe:</u>  <u>Baking:</u></p>	
14	<p><b>Mask Exposure + Develop</b>  <u>Machine:</u> MLA + developer  <u>Layer to expose:</u> <ul style="list-style-type: none"> <li>Layer #9</li> </ul>         Invert Mask polarity:          Exposure window: See #04          Alignment Cross: See #08  <u>Dose:</u>  <u>Development:</u></p>	

15	<p>Dry Etching</p> <p><u>Machine:</u> Corial</p> <p><u>Recipe:</u></p> <p><u>Time:</u></p>	
16	<p>Stripping</p> <p><u>Ultrasonic bath &amp; Acetone</u></p>	
17	<p>Annealing</p> <p><u>1 hour @ 900°C</u></p>	
18	<p>Dicing</p>	